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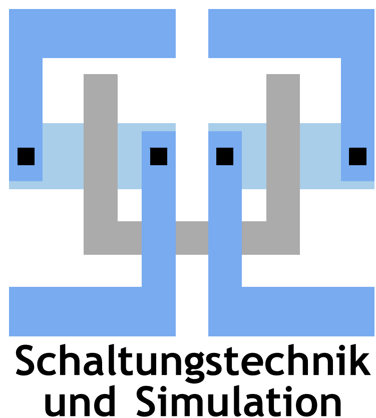
PXD9 Kapton Footprint Bondpad Optimizations



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Kapton & TML Meeting

EVO

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Changes to Footprint

- Removed obsolete differential signals: DHP_FCK, DHP_RST
- use freed space to reorder sense lines
  - 4 senselines from top bond layer to middle bond layer
- Increase power bondpads to not exceed 200mA/bond
  - DHPCore ca. 700mA -> 5bonds=1000mA
  - DHPIO ca. 220mA -> 4bonds=800mA
  - DCD_DVDD ca. 720mA -> 5bonds=1000mA
  - RefIn ca. 200mA -> 4bonds=800mA
- New sizes with a bondpitch of 100µm
  - DHPCore 530µm
  - DHPIO 430µm
  - DCD_DVDD 530µm
  - RefIn 430µm

Kapton_Footprint_A

- used in inner_fwd and outer_bwd

Kapton_Footprint_B

- used in outer_fwd and inner_bwd

Other Changes / ToDo

- increased with of differential lines to 30µm
- increased spacing of termination resistors to 200µm
- increased width of power routing on copper layer

- designs are LVS and DRC clean

- ToDo:
  - incorporate change in inner bwd and outer fwd modules

Thank you!